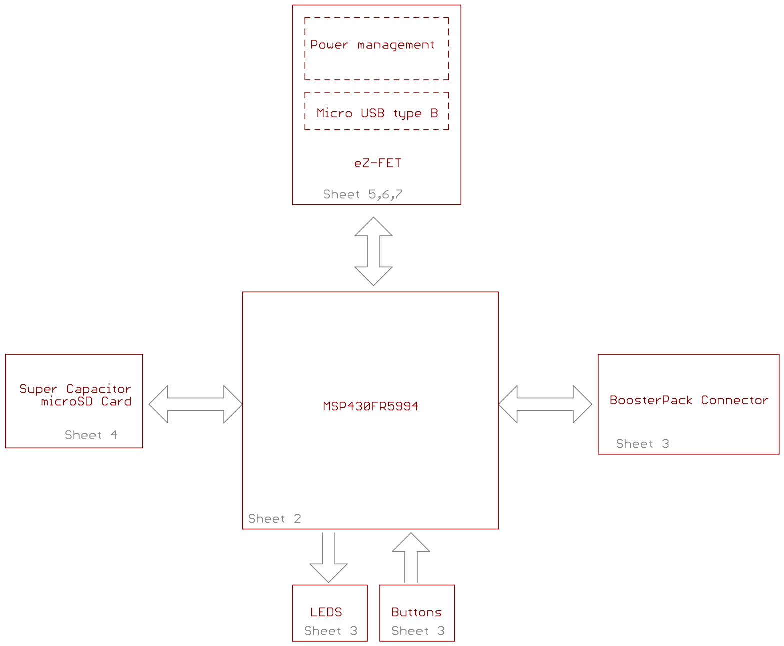

COMPANY: Texas Instruments		
TITLE: MSP-EXP430FR5994		
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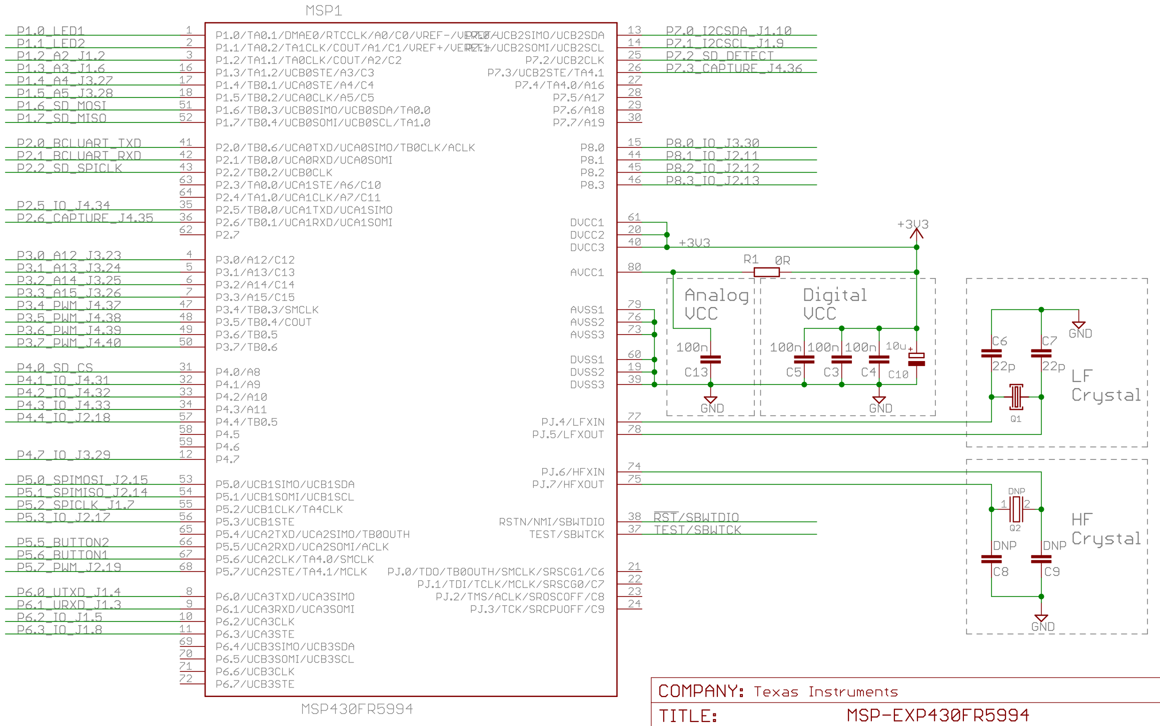
Target MSP430FR5994 MCU



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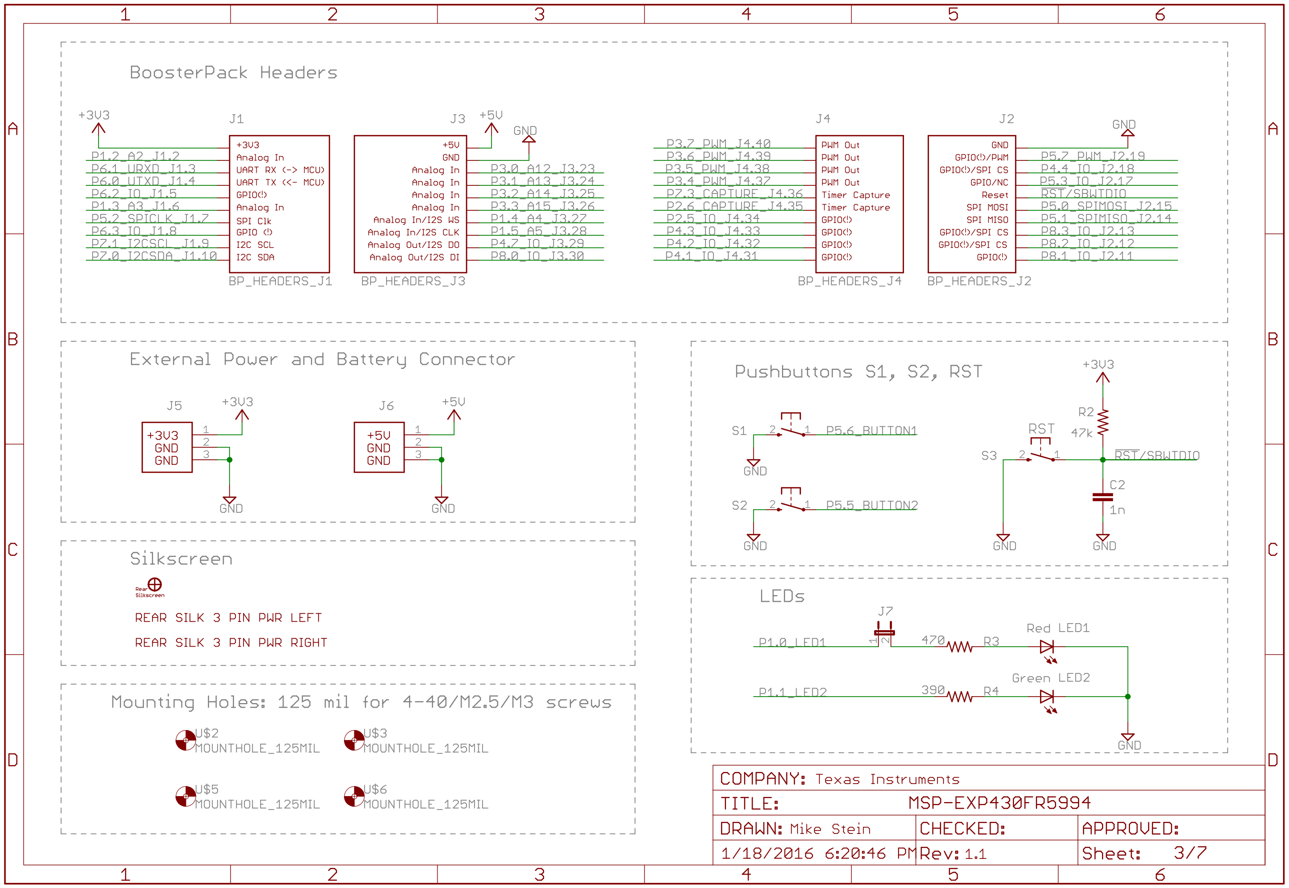

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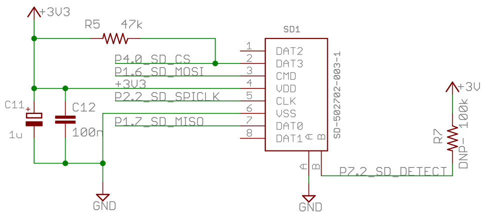
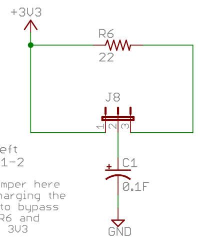
microSD Memory Card Interface



DNP R7 for accurate LPM current.
Use internal MSP pullup in software,
or else populate R7

Super Capacitor



Use

Jumper Left
Position 1-2

Connect jumper here when discharging the capacitor to bypass resistors R6 and connect to 3V3

Charge

Jumper Right
Position 2-3

Connect jumper here when charging capacitor to use current limiting resistor R6

Bypass/Disconnect

Jumper not connected
Hang off single pin

When jumper is not in the "Charge" or "Use" position, the capacitor is not connected (bypassed). We recommend hanging the jumper from 1 pin so it does not get lost

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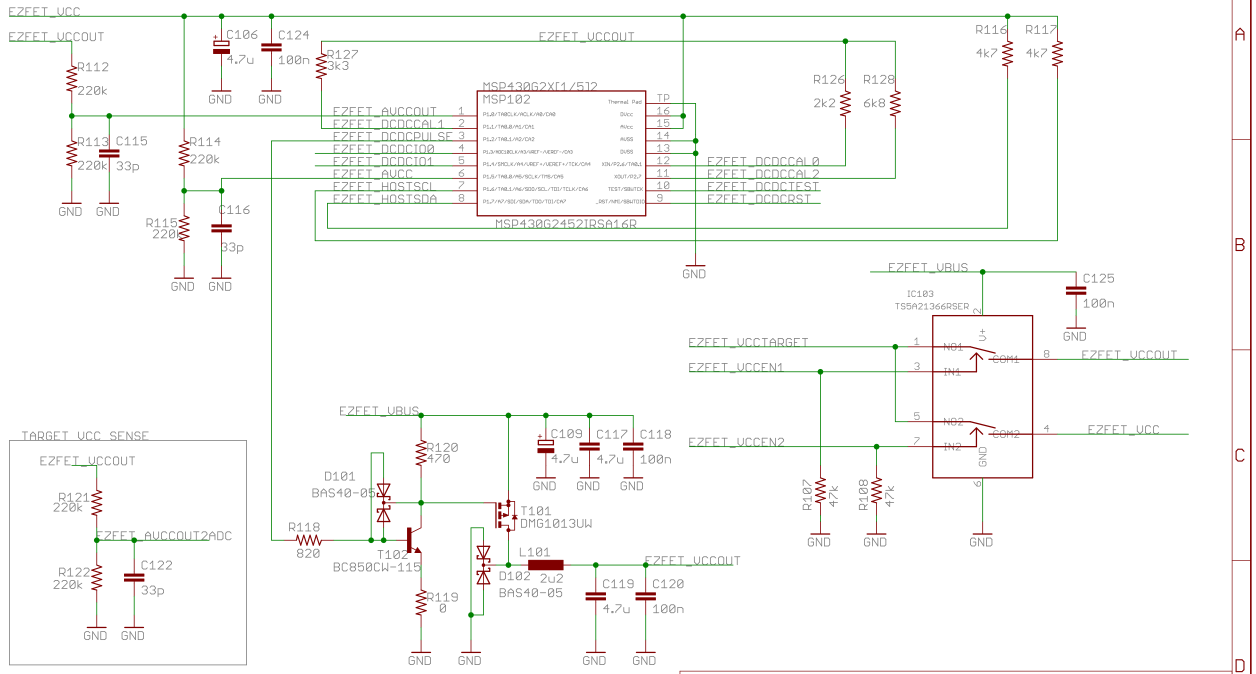
Software-controlled DCDC converter

Energy measurement method protected under U.S. Patent
Application 13/329,073 and subsequent patent applications



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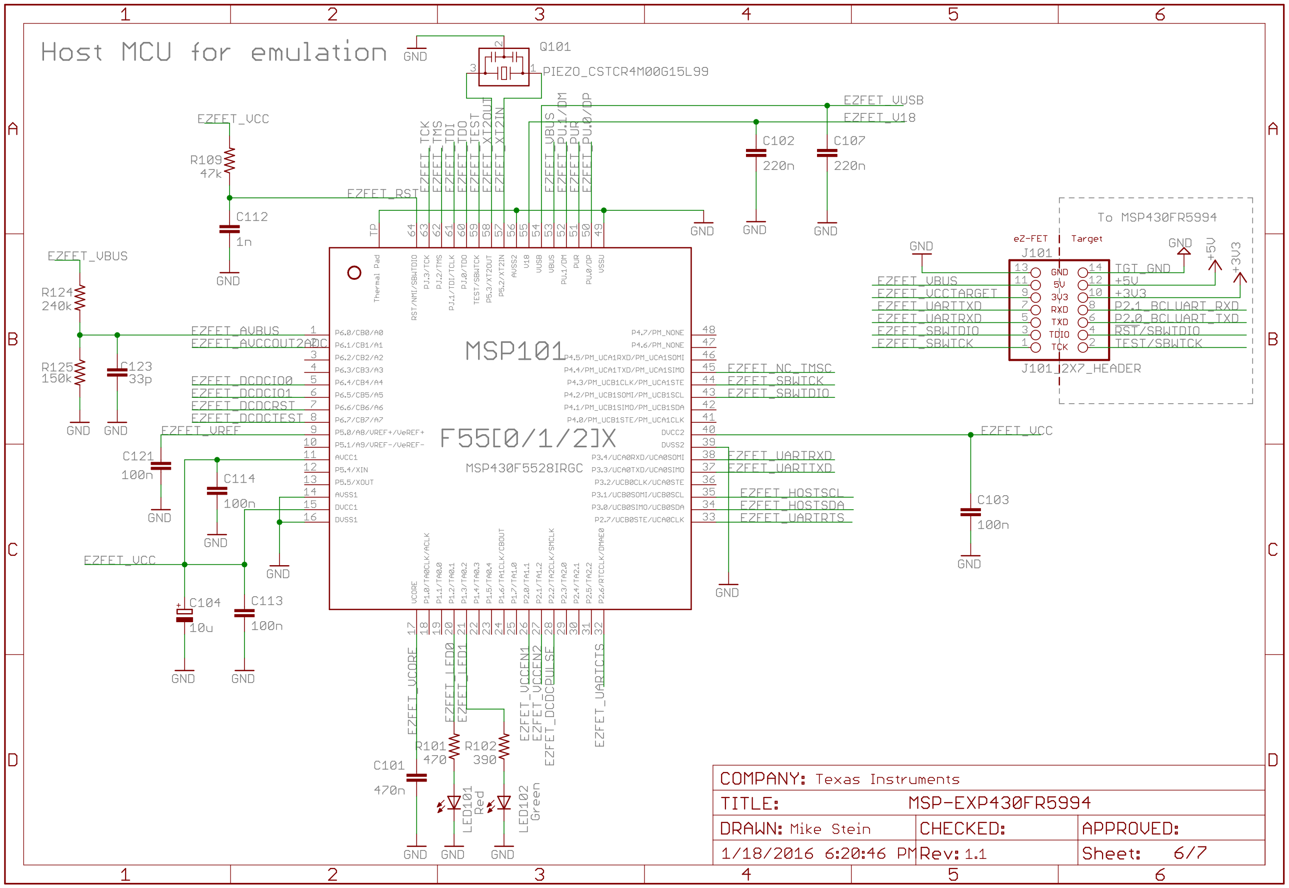

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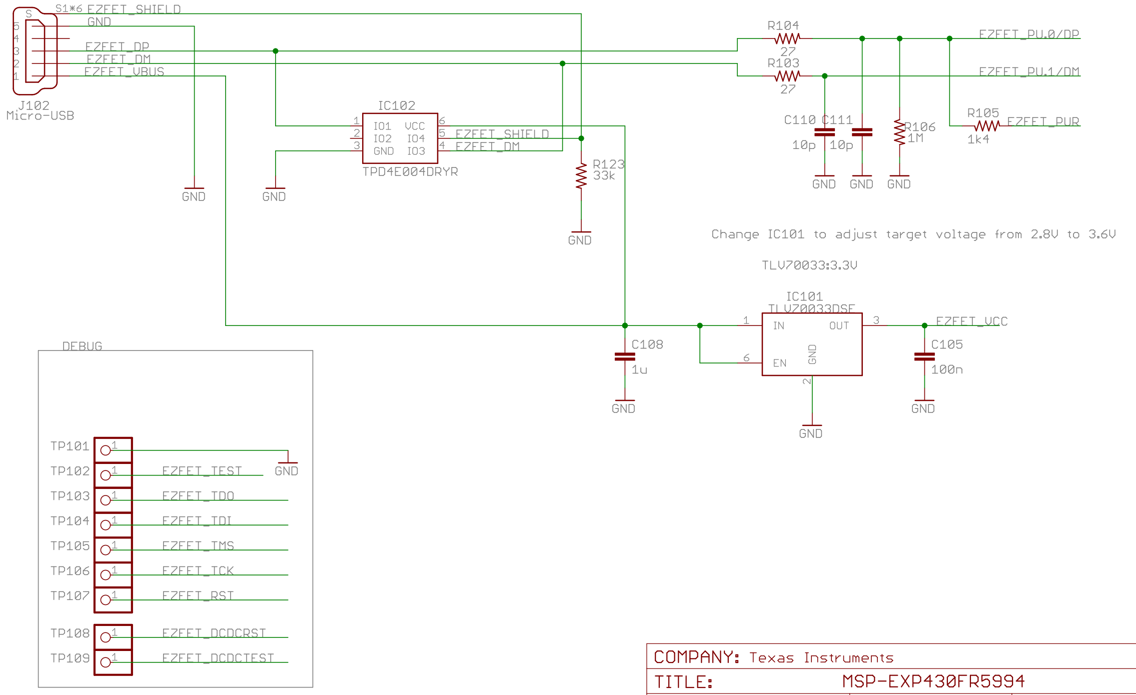
USB interface and power supply



Change IC101 to adjust target voltage from 2.8V to 3.6V

TLV70033:3.3V

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